

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In the Claims.

36. (Amended) A method, comprising the steps of:

5                   depositing first conductive film over a first insulating layer having a hole formed therein, the first conductive film being thicker over a top surface of the first insulating layer than on a side surface of the hole;

depositing a second conductive film over the first conductive film;

depositing a third conductive film over the second conductive film and within the hole;

10                  etching the third conductive film selective to the second conductive film to expose the second conductive film around the hole, the third conductive film being only within the hole and having a plug top that extends above the top surface of the first insulating layer but below a top surface of the second conductive film; and

15                  selectively etching the first and second conductive films relative to the third conductive film to expose the top surface of the first insulating film around the hole, the first and second conductive films being only within the hole.

*Please cancel claim 37.*

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